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Title of Invention: SEMICONDUCTOR PACKAGE  
HAVING REDUCED THICKNESS  
First Named Inventor: TAE LEE  
Domestic/Foreign Application: Domestic Application  
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## TRANSMITTAL

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<p>Application Number: 10/763859 </p> <p>Date: 2004-01-23</p> <p>First Named Applicant: TAE HEON LEE</p> <p>Confirmation Number: 8528</p> <p>Attorney Docket Number: AMKOR053G</p>										
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids3-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids3-usidst.xml		us-ids.dtd		us-ids.xsl
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Electronic Version v18

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	10	5646831	1997-07-08	Manteghi
	11	5650663	1997-07-22	Parthasaranthi
	12	5661088	1997-08-26	Tessier et al.
	13	5665996	1997-09-09	Williams et al.
	14	5673479	1997-10-07	Hawthorne
	15	5683806	1997-11-04	Sakumoto et al.
	16	5689135	1997-11-18	Ball
	17	5696666	1997-12-09	Miles et al.
	18	5701034	1997-12-23	Marrs
	19	5703407	1997-12-30	Hori
	20	5710064	1998-01-20	Song et al.
	21	5724233	1998-03-03	Honda et al.
	22	5723899	1998-03-03	Shin
	23	5726493	1998-03-10	Yamashita
	24	5736432	1998-04-07	Mackessy
	25	5745984	1998-05-05	Cole, Jr. et al.
	26	5753532	1998-05-19	Sim
	27	5753977	1998-05-19	Kusaka et al.
	28	5766972	1998-06-16	Takahashi et al.
	29	5770888	1998-06-23	Song et al.
	30	5776798	1998-07-07	Quan et al.
	31	5783861	1998-07-21	Son
	32	5801440	1998-09-01	Chu et al.
	33	5814877	1998-09-29	Diffenderfer et al.
	34	5814881	1998-09-29	Alagaratnam et al.
	35	5814883	1998-09-29	Sawai et al.
	36	5814884	1998-09-29	Davis et al.
	37	5817540	1998-10-06	Wark
	38	5818105	1998-10-06	Kouda
	39	5821457	1998-10-13	Mosley et al.
	40	5821615	1998-10-13	Lee
	41	5834830	1998-11-10	Cho
	42	5835988	1998-11-10	Ishii
	43	5844306	1998-12-01	Fujita et al.
	44	5856911	1999-01-05	Riley
	45	5859471	1999-01-12	Kuraishi et al.

	46	5866939	1999-02-02	Shin et al.
	47	5871782	1999-02-16	Choi
	48	5874784	1999-02-23	Aoki, et al.
	49	5877043	1999-03-02	Alcoe et al.
	50	5886397	1999-03-23	Ewer

Signature

Examiner Name	Date